

# RCJ160N20 Nch 200V 16A Power MOSFET

| V <sub>DSS</sub>           | 200V  |
|----------------------------|-------|
| R <sub>DS(on)</sub> (Max.) | 180mΩ |
| I <sub>D</sub>             | ±16A  |
| P <sub>D</sub>             | 85W   |

#### Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant
- 6) 100% Avalanche tested

## Application

Switching Power Supply

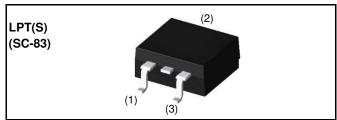
Automotive Motor Drive

Automotive Solenoid Drive

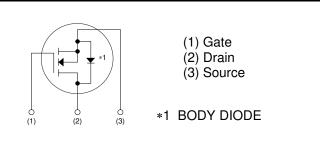
## ●Absolute maximum ratings(T<sub>a</sub> = 25°C)

| Paramete                                   | Symbol                  | Value                        | Unit        |    |
|--|-------------------------|------------------------------|-------------|----|
| Drain - Source voltage                     | V <sub>DSS</sub>        | 200                          | V           |    |
| Continuous dusin suurent                   | $T_c = 25^{\circ}C$     | I <sub>D</sub> <sup>*1</sup> | ±16         | А  |
| Continuous drain current                   | $T_c = 100^{\circ}C$    | I <sub>D</sub> <sup>*1</sup> | ±8.7        | А  |
| Pulsed drain current                       | I <sub>D,pulse</sub> *2 | ±64                          | А           |    |
| Gate - Source voltage                      |                         | V <sub>GSS</sub>             | ±30         | V  |
| Avalanche energy, single puls              | e                       | E <sub>AS</sub> *3           | 20.7        | mJ |
| Avalanche current                          |                         | I <sub>AR</sub> *3           | 8.0         | А  |
| $T_c = 25^{\circ}C$                        |                         | P <sub>D</sub>               | 85          | W  |
| Power dissipation $T_a = 25^{\circ}C^{*4}$ |                         | P <sub>D</sub>               | 1.56        | W  |
| Junction temperature                       |                         | Tj                           | 150         | °C |
| Range of storage temperature               |                         | T <sub>stg</sub>             | -55 to +150 | °C |

#### Outline



#### Inner circuit



### Packaging specifications

|      | Packaging       | Taping    |
|------|-----------------|-----------|
|      | Reel size (mm)  | 330       |
| Tuno | Tape width (mm) | 24        |
| Туре | Quantity (pcs)  | 1,000     |
|      | Taping code     | TL        |
|      | Marking         | RCJ160N20 |

#### Thermal resistance

| Parameter                                    | Symbol     | Values |      |      | Unit |
|--|------------|--------|------|------|------|
| Farameter                                    | Symbol     | Min.   | Тур. | Max. | Unit |
| Thermal resistance, junction - case          | $R_{thJC}$ | -      | -    | 1.46 | °C/W |
| Thermal resistance, junction - ambient *4    | $R_{thJA}$ | -      | -    | 80   | °C/W |
| Soldering temperature, wavesoldering for 10s | $T_{sold}$ | -      | -    | 265  | °C   |

# •Electrical characteristics( $T_a = 25^{\circ}C$ )

| Paramator                                      | Symbol                 | Conditions                        |      | Values |      |      |  |
|--|------------------------|-----------------------------------|------|--------|------|------|--|
| Parameter                                      | Symbol                 | Conditions                        | Min. | Тур.   | Max. | Unit |  |
| Drain - Source breakdown voltage               | $V_{(BR)DSS}$          | $V_{GS} = 0V, I_D = 1mA$          | 200  | -      | -    | V    |  |
|  |                        | $V_{DS} = 200V, V_{GS} = 0V$      |      |        | 10   |      |  |
| Zero gate voltage drain current                |                        | T <sub>j</sub> = 25°C             | -    | -      | 10   | μA   |  |
|  | I <sub>DSS</sub>       | $V_{DS} = 200V, V_{GS} = 0V$      |      | -      | 100  |      |  |
|  |                        | T <sub>j</sub> = 125°C            | -    |        |      |      |  |
| Gate - Source leakage current                  | I <sub>GSS</sub>       | $V_{GS} = \pm 30V, \ V_{DS} = 0V$ | -    | -      | ±100 | nA   |  |
| Gate threshold voltage                         | V <sub>GS (th)</sub>   | $V_{DS} = 10V, I_{D} = 1mA$       | 3.25 | -      | 5.25 | V    |  |
|  |                        | $V_{GS} = 10V, I_D = 8.0A$        | -    | 135    | 180  |      |  |
| Static drain - source<br>on - state resistance | $R_{DS(on)}$ *5        | $V_{GS} = 10V, I_D = 8.0A$        |      | 205    | 410  | mΩ   |  |
|  |                        | T <sub>j</sub> = 125°C            | -    | 295    | 410  |      |  |
| Forward transfer admittance                    | <b>g</b> <sub>fs</sub> | $V_{DS} = 10V, I_{D} = 8.0A$      | 4    | 8      | -    | S    |  |

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## •Electrical characteristics( $T_a = 25^{\circ}C$ )

| Parameter                    | Symbol                 | Conditions                         | Values |      |      | Unit |
|------------------------------|------------------------|------------------------------------|--------|------|------|------|
| Farameter                    | Symbol                 | Conditions                         | Min.   | Тур. | Max. | Unit |
| Input capacitance            | C <sub>iss</sub>       | $V_{GS} = 0V$                      | -      | 1370 | -    |      |
| Output capacitance           | C <sub>oss</sub>       | V <sub>DS</sub> = 25V              | -      | 95   | -    | pF   |
| Reverse transfer capacitance | C <sub>rss</sub>       | f = 1MHz                           | -      | 50   | -    |      |
| Turn - on delay time         | t <sub>d(on)</sub> *5  | $V_{DD} \simeq 100V, V_{GS} = 10V$ | -      | 27   | -    |      |
| Rise time                    | t <sub>r</sub> *5      | I <sub>D</sub> = 8.0A              | -      | 47   | -    | 20   |
| Turn - off delay time        | t <sub>d(off)</sub> *5 | R <sub>L</sub> = 12.5Ω             | -      | 42   | -    | ns   |
| Fall time                    | t <sub>f</sub> *5      | $R_G = 10\Omega$                   | -      | 17   | -    |      |

## •Gate Charge characteristics( $T_a = 25^{\circ}C$ )

| Parameter            | Symbol                 | Conditions                        | Values |      |      | Unit |
|----------------------|------------------------|-----------------------------------|--------|------|------|------|
| Farameter            | Symbol Conditions -    |                                   | Min.   | Тур. | Max. | Unit |
| Total gate charge    | $Q_g^{*5}$             | $V_{DD} \simeq 100V$              | -      | 26   | -    |      |
| Gate - Source charge | ${\sf Q_{gs}}^{*5}$    | I <sub>D</sub> = 16A              | -      | 10   | -    | nC   |
| Gate - Drain charge  | $Q_{gd}$ *5            | $V_{GS} = 10V$                    | -      | 11   | -    |      |
| Gate plateau voltage | V <sub>(plateau)</sub> | $V_{DD} \simeq 100V, \ I_D = 16A$ | -      | 7.0  | -    | V    |

## ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

| Parameter                 | Symbol                        | Conditions                 | Values |      |      | Unit |
|---------------------------|-------------------------------|----------------------------|--------|------|------|------|
| Farameter                 | Symbol                        | Symbol Conditions –        |        | Тур. | Max. | Unit |
| Continuous source current | $I_{S}^{*1}$                  | T <sub>c</sub> = 25°C      | -      | -    | 16   | А    |
| Pulsed source current     | $I_{SM}$ *2                   | $r_{c} = 25.0$             | -      | -    | 64   | А    |
| Forward voltage           | $V_{SD}$ *5                   | $V_{GS} = 0V, I_{S} = 16A$ | -      | -    | 1.5  | V    |
| Reverse recovery time     | t <sub>rr</sub> *5            | I <sub>S</sub> = 8.0A      | -      | 85   | -    | ns   |
| Reverse recovery charge   | Q <sub>rr</sub> <sup>*5</sup> | di/dt = 100A/µs            | -      | 300  | -    | nC   |

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10 $\mu s,$  Duty cycle  $\leq$  1%

\*3 L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, Rg = 25 $\Omega$ , starting T<sub>j</sub> = 25°C

\*4 Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

\*5 Pulsed

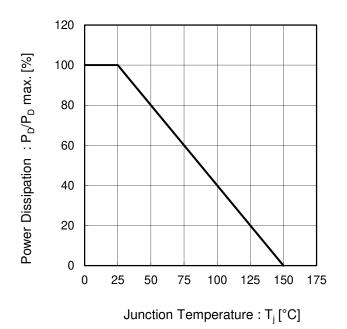
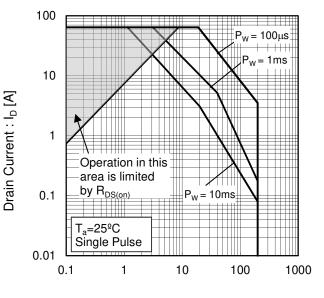


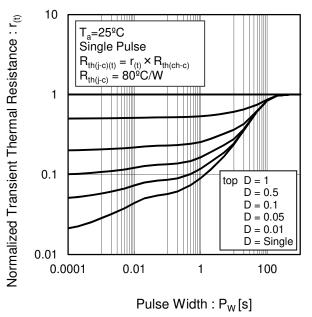
Fig.1 Power Dissipation Derating Curve

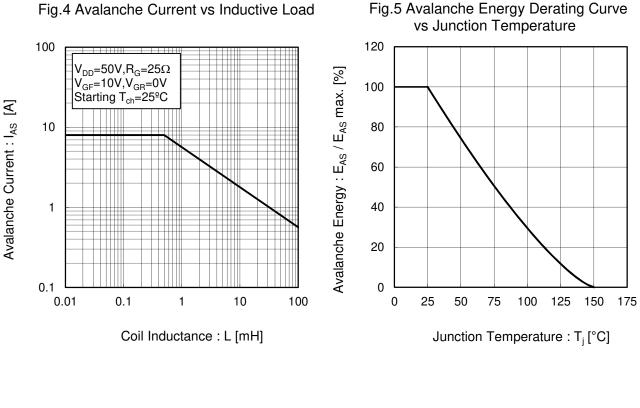
Fig.2 Maximum Safe Operating Area



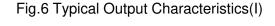
Drain - Source Voltage :  $V_{DS}$  [V]

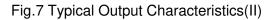
#### Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

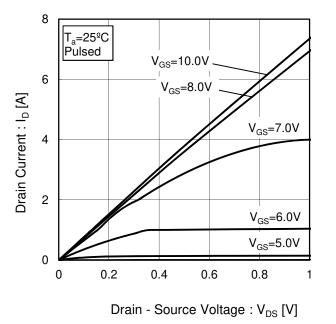


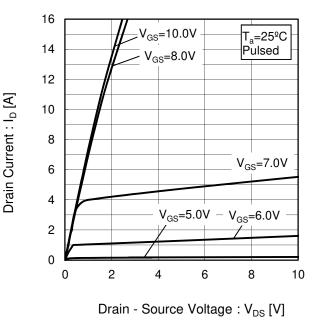


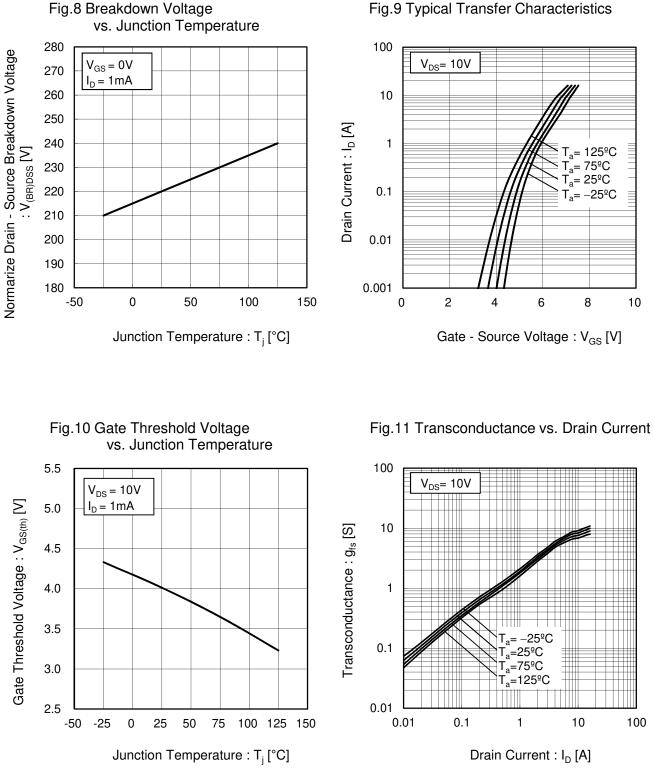
## Fig.4 Avalanche Current vs Inductive Load

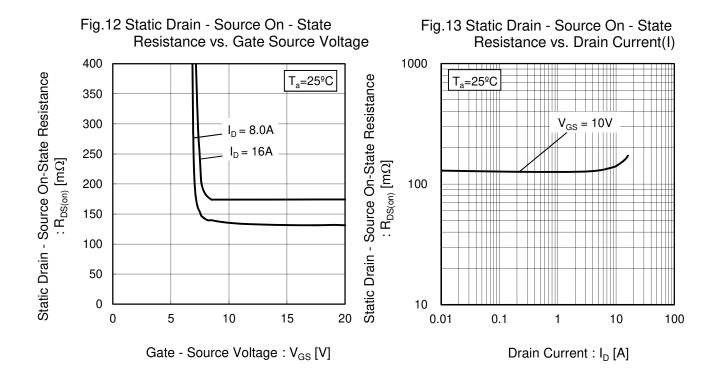




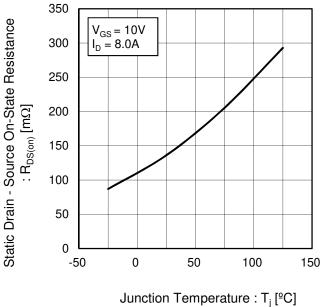


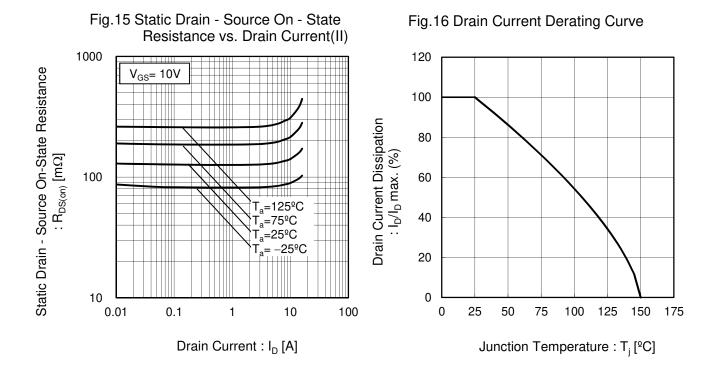




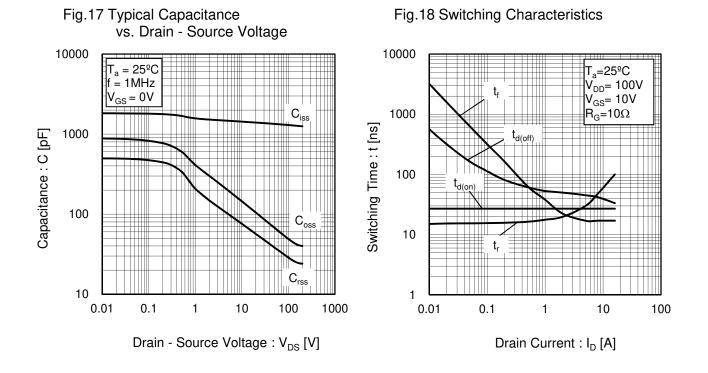


# Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

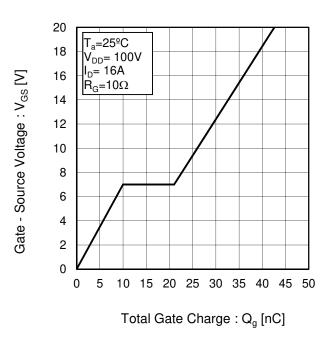


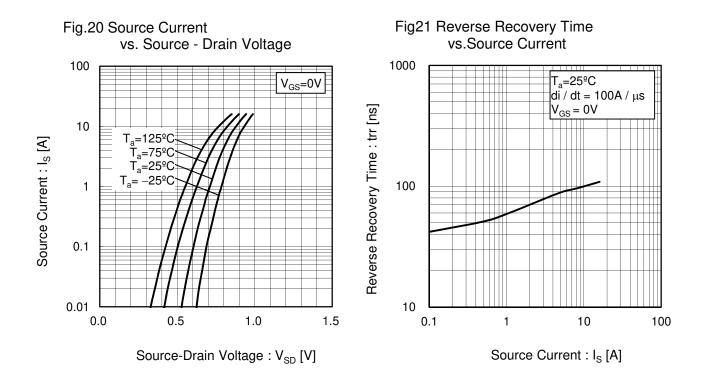






## Fig.19 Dynamic Input Characteristics





#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

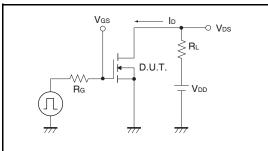


Fig.2-1 Gate Charge Measurement Circuit

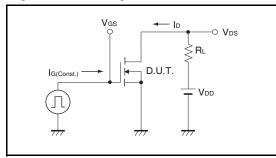
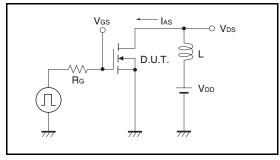


Fig.3-1 Avalanche Measurement Circuit



#### Fig.1-2 Switching Waveforms

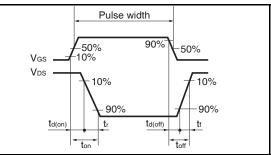
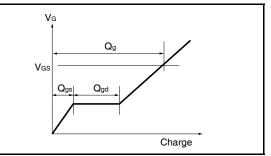
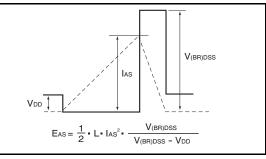
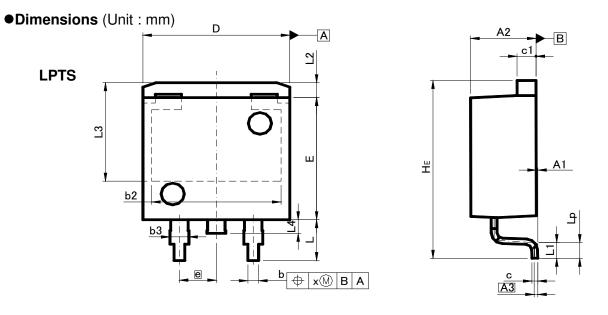


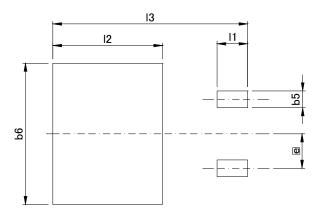
Fig.2-2 Gate Charge Waveform



## Fig.3-2 Avalanche Waveform







## Patterm of terminal position areas

| DIM | MILIM | ETERS | INC   | HES   |
|-----|-------|-------|-------|-------|
| DIM | MIN   | MAX   | MIN   | MAX   |
| A1  | 0.00  | 0.30  | 0     | 0.012 |
| A2  | 4.30  | 4.70  | 0.169 | 0.185 |
| A3  | 0.1   | 25    | 0.    | 01    |
| b   | 0.68  | 0.98  | 0.027 | 0.039 |
| b2  | 8.    | 90    | 0.    | 35    |
| b3  | 1.14  | 1.44  | 0.045 | 0.057 |
| с   | 0.30  | 0.60  | 0.012 | 0.024 |
| c1  | 1.10  | 1.50  | 0.043 | 0.059 |
| D   | 9.80  | 10.40 | 0.386 | 0.409 |
| E   | 8.80  | 9.20  | 0.346 | 0.362 |
| е   | 2.    | 54    | 0.10  |       |
| HE  | 12.80 | 13.40 | 0.504 | 0.528 |
| L   | 2.70  | 3.30  | 0.106 | 0.13  |
| L1  | 0.90  | 1.50  | 0.035 | 0.059 |
| L2  | 1.10  |       | 0.0   | )43   |
| L3  | 7.25  |       | 0.2   | 85    |
| L4  | 1.00  |       | 0.0   | 39    |
| Lp  | 0.90  | 1.50  | 0.035 | 0.059 |
| х   | -     | 0.25  | -     | 0.01  |

| DIM | MILIMETERS |       | INC | HES   |
|-----|------------|-------|-----|-------|
| DIN | MIN        | MAX   | MIN | MAX   |
| b5  | -          | 1.23  | -   | 0.049 |
| b6  | -          | 10.40 | -   | 0.409 |
| 1   | -          | 2.10  | -   | 0.083 |
| 12  | -          | 7.55  | -   | 0.297 |
| 13  | -          | 13.40 | -   | 0.528 |

Dimension in mm/inches

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|---|----------------------|
|---|----------------------|

| JAPAN  | USA     | EU         | CHINA   |
|--------|---------|------------|---------|
| CLASSⅢ | CLASSⅢ  | CLASS II b | CLASSII |
| CLASSⅣ | CLASSII | CLASSⅢ     | CLASSI  |

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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